

Jc1030

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10050166	FILING DATE 01/18/2002	CLASS 438 ¹⁵⁷	SUBCLASS ---	GAU 2812	EXAMINER Ponetch
**APPLICANTS: Horibe Hiroshi: 720					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-256892 09/27/2001					
PG PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 50090-466	
Verified and Acknowledged Examiners's initials					
TITLE : Semiconductor device and wire bonding apparatus					

U.S. DEPT. OF COMM./PAT & TM-PTO-435L(R) rev. 12-94

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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